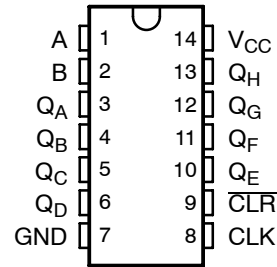


SN54HC164, SN74HC164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 20$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- AND-Gated (Enable/Disable) Serial Inputs
- Fully Buffered Clock and Serial Inputs
- Direct Clear

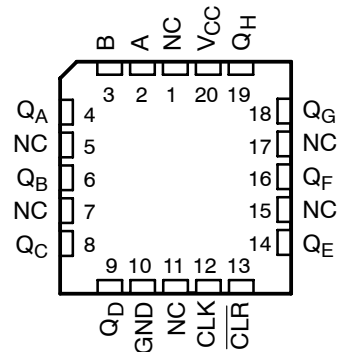
SN54HC164 . . . J OR W PACKAGE
SN74HC164 . . . D, N, NS, OR PW PACKAGE
(TOP VIEW)



description/ordering information

These 8-bit shift registers feature AND-gated serial inputs and an asynchronous clear (CLR) input. The gated serial (A and B) inputs permit complete control over incoming data; a low at either input inhibits entry of the new data and resets the first flip-flop to the low level at the next clock (CLK) pulse. A high-level input enables the other input, which then determines the state of the first flip-flop. Data at the serial inputs can be changed while CLK is high or low, provided the minimum setup time requirements are met. Clocking occurs on the low-to-high-level transition of CLK.

SN54HC164 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC164N	SN74HC164N
	SOIC – D	Tube of 50	SN74HC164D	HC164
		Reel of 2500	SN74HC164DRG3	
		Reel of 250	SN74HC164DT	
	SOP – NS	Reel of 2000	SN74HC164NSR	HC164
	TSSOP – PW	Tube of 90	SN74HC164PW	HC164
		Reel of 2000	SN74HC164PWR	
		Reel of 250	SN74HC164PWT	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54HC164J	SNJ54HC164J
	CFP – W	Tube of 150	SNJ54HC164W	SNJ54HC164W
	LCCC – FK	Tube of 55	SNJ54HC164FK	SNJ54HC164FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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SN54HC164, SN74HC164
8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

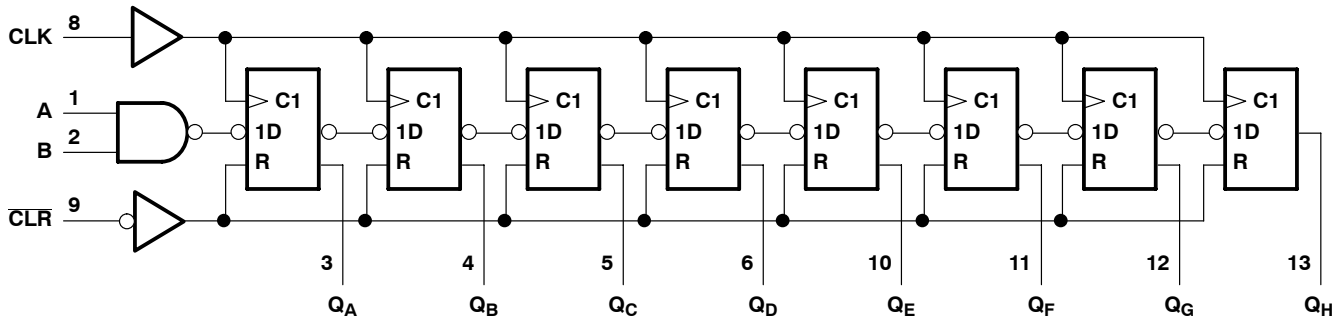
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FUNCTION TABLE

INPUTS				OUTPUTS		
CLR	CLK	A	B	Q _A	Q _B . . . Q _H	
L	X	X	X	L	L	L
H	L	X	X	Q _{A0}	Q _{B0}	Q _{H0}
H	↑	H	H	H	Q _{An}	Q _{Gn}
H	↑	L	X	L	Q _{An}	Q _{Gn}
H	↑	X	L	L	Q _{An}	Q _{Gn}

Q_{A0}, Q_{B0}, Q_{H0} = the level of Q_A, Q_B, or Q_H, respectively, before the indicated steady-state input conditions were established
Q_{An}, Q_{Gn} = the level of Q_A or Q_G before the most recent ↑ transition of CLK: indicates a 1-bit shift

logic diagram (positive logic)



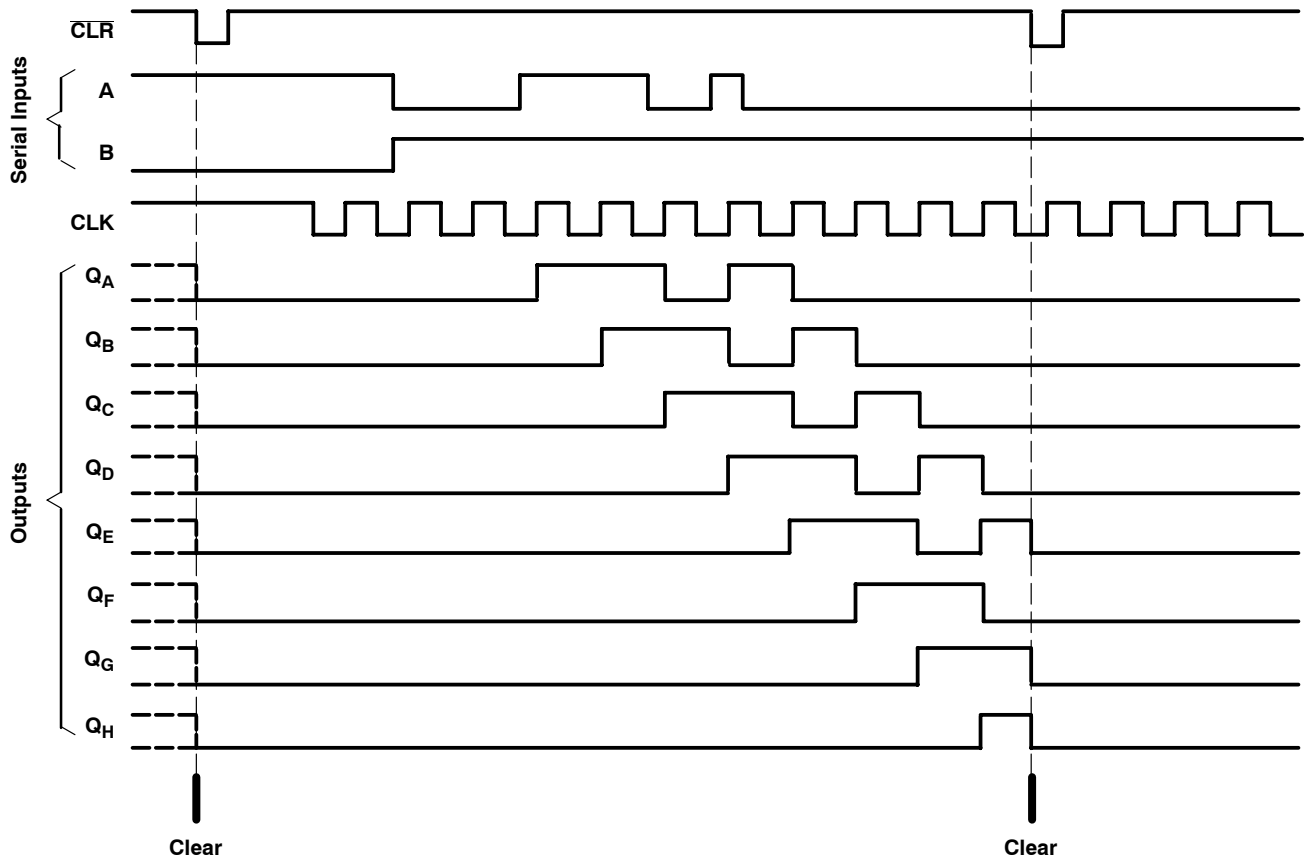
Pin numbers shown are for the D, J, N, NS, PW, and W packages.



SN54HC164, SN74HC164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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typical clear, shift, and clear sequence



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2):	
D package	86°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.



SN54HC164, SN74HC164

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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recommended operating conditions (see Note 3)

			SN54HC164			SN74HC164			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5			0.5			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 6 V	1.8			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv [†]	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		−55	125		−40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

[†] If this device is used in the threshold region (from $V_{IL\text{max}} = 0.5\text{ V}$ to $V_{IH\text{min}} = 1.5\text{ V}$), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_f = 1000\text{ ns}$ and $V_{CC} = 2\text{ V}$ does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC164		SN74HC164		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V_{OH}	$V_I = V_{IH}\text{ or }V_{IL}$	$I_{OH} = -20\text{ }\mu\text{A}$	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		$I_{OH} = -4\text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2\text{ mA}$	6 V	5.48	5.8		5.2		5.34		
V_{OL}	$V_I = V_{IH}\text{ or }V_{IL}$	$I_{OL} = 20\text{ }\mu\text{A}$	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		$I_{OL} = 4\text{ mA}$	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2\text{ mA}$	6 V		0.15	0.26		0.4		0.33	
I_I	$V_I = V_{CC}\text{ or }0$		6 V		± 0.1	± 100		± 1000		± 1000	nA
I_{CC}	$V_I = V_{CC}\text{ or }0, I_O = 0$		6 V			8		160		80	μA
C_i			2 V to 6 V		3	10		10		10	pF



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SN54HC164, SN74HC164 8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V_{CC}	$T_A = 25^\circ\text{C}$		SN54HC164		SN74HC164		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency	2 V		6		4.2		5	MHz
		4.5 V		31		21		25	
		6 V		36		25		28	
t_w	$\overline{\text{CLR}}$ low	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	CLK high or low	2 V	80		120		100		
		4.5 V	16		24		20		
		6 V	14		20		18		
t_{su}	Data	2 V	100		150		125		ns
		4.5 V	20		30		25		
		6 V	17		25		21		
	$\overline{\text{CLR}}$ inactive	2 V	100		150		125		
		4.5 V	20		30		25		
		6 V	17		25		21		
t_h	Hold time, data after CLK \uparrow	2 V	5		5		5		ns
		4.5 V	5		5		5		
		6 V	5		5		5		

switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC164		SN74HC164		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			2 V	6	10		4.2		5		MHz
			4.5 V	31	54		21		25		
			6 V	36	62		25		28		
t_{PHL}	$\overline{\text{CLR}}$	Any Q	2 V		140	205		295		255	ns
			4.5 V		28	41		59		51	
			6 V		24	35		51		46	
t_{pd}	CLK	Any Q	2 V		115	175		265		220	
			4.5 V		23	35		53		44	
			6 V		20	30		45		38	
t_t			2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
C_{pd} Power dissipation capacitance	No load	135	pF



TEXAS
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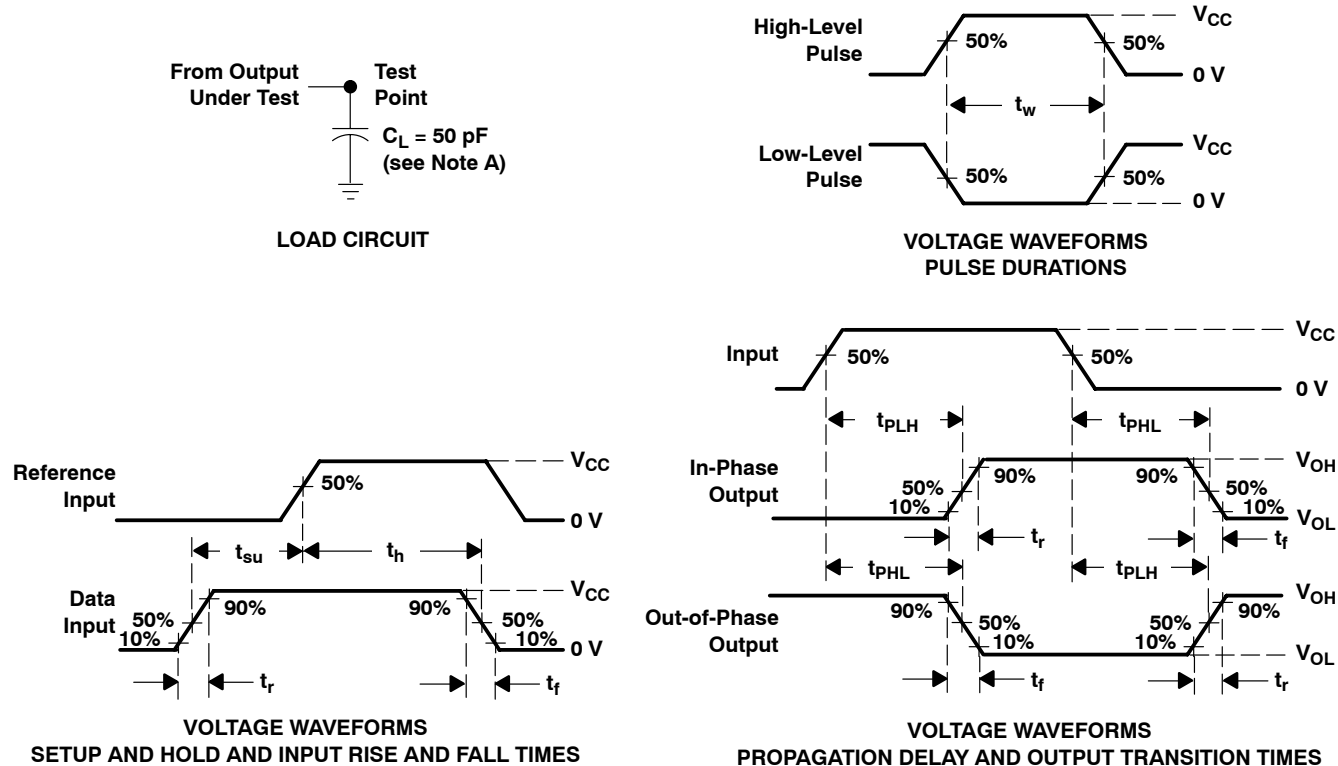
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SN54HC164, SN74HC164

8-BIT PARALLEL-OUT SERIAL SHIFT REGISTERS

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PARAMETER MEASUREMENT INFORMATION



- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
5962-8416201VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
5962-8416201VDA	ACTIVE	CFP	W	14	25	TBD	A42	N / A for Pkg Type	
84162012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Call TI	
8416201CA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Call TI	
SN54HC164J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SN74HC164D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	
SN74HC164DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC164N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	
SN74HC164NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	
SN74HC164NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74HC164NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SN74HC164PWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
SNJ54HC164FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
SNJ54HC164J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	
SNJ54HC164W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN54HC164, SN54HC164-SP, SN74HC164 :

- Catalog: [SN74HC164](#), [SN54HC164](#)
- Military: [SN54HC164](#)
- Space: [SN54HC164-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC164DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC164DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC164DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC164DT	SOIC	D	14	250	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74HC164NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74HC164PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC164PWT	TSSOP	PW	14	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC164DR	SOIC	D	14	2500	367.0	367.0	38.0
SN74HC164DR	SOIC	D	14	2500	333.2	345.9	28.6
SN74HC164DRG4	SOIC	D	14	2500	333.2	345.9	28.6
SN74HC164DRG4	SOIC	D	14	2500	367.0	367.0	38.0
SN74HC164DT	SOIC	D	14	250	367.0	367.0	38.0
SN74HC164NSR	SO	NS	14	2000	367.0	367.0	38.0
SN74HC164PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
SN74HC164PWT	TSSOP	PW	14	250	367.0	367.0	35.0

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

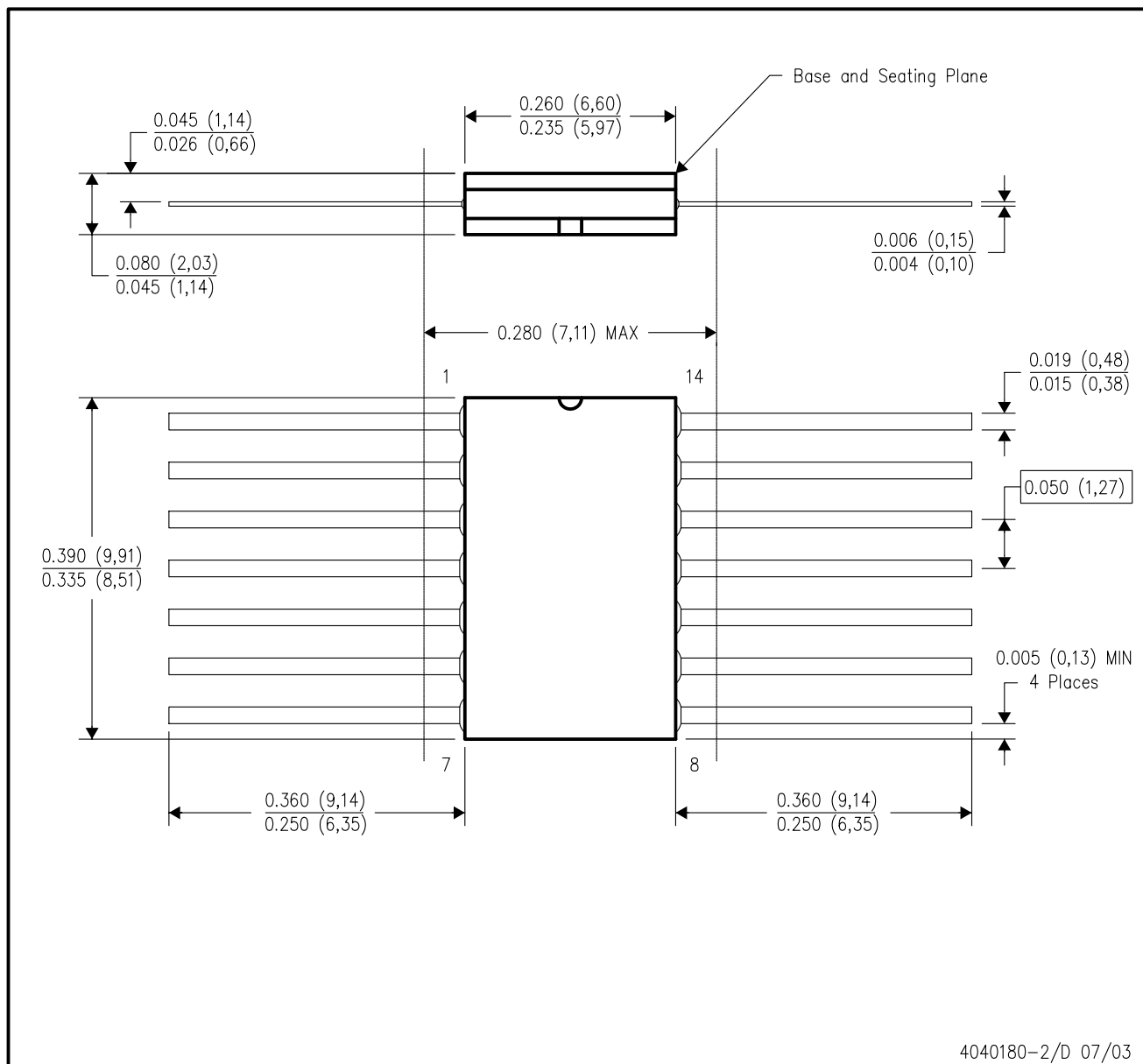


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only.
 - Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE

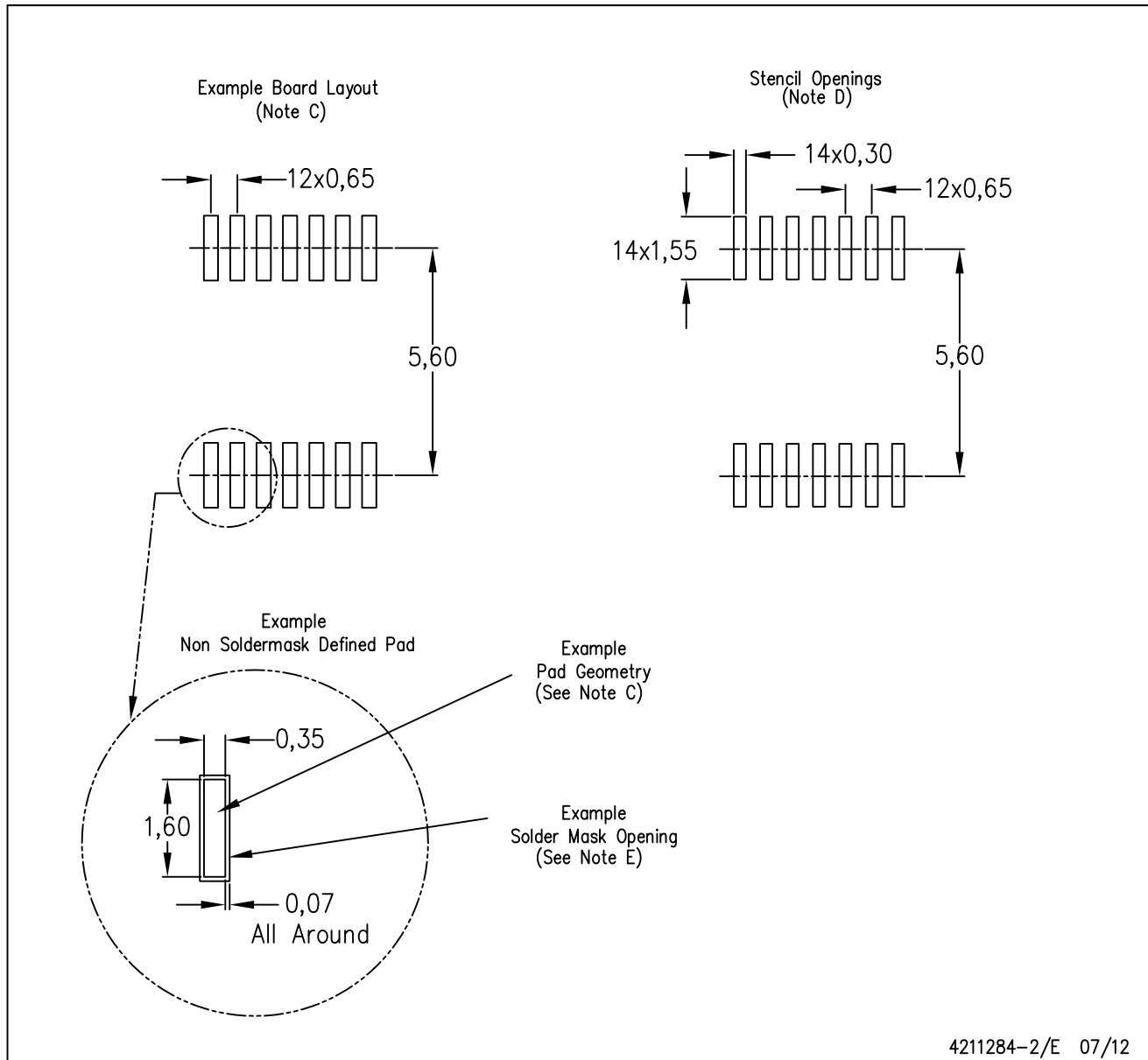


4040064-3/G 02/11

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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